

• Product Summary

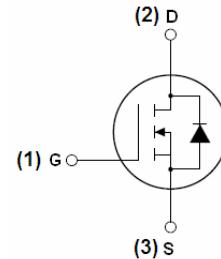
Part #	V _{DS}	R _{DS(on).typ} (@V _{GS} =10V)	R _{DS(on).typ} (@V _{GS} =4.5V)	I _D
EFM250N06D	60V	23mΩ	28mΩ	30A

• Description

- The EFM250N06D is the high cell density trenched
- N-ch MOSFETs which provide excellent
- RDSON and gate charge for most of the
- synchronous buck converter applications.
- The EFM250N06D meet the RoHS and Green
- Product requirement, 100 % EAS guaranteed
- with full function reliability approved.

• Application

- Super Low Gate Charge 100% EAS Guaranteed
- Green Device Available Excellent CdV/dt effect decline
- Advanced high cell density Trench technology



N-Channel MOSFET



TO-252-2L

• Ordering Information:

Part NO.	EFM250N06D
Marking	250N06D****
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

• Absolute Maximum Ratings (T_C=25°C)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	30	A
Drain Current-Pulsed ^(Note 1)	I _{DM}	74	A
Maximum Power Dissipation	P _D	50	W
Single pulse avalanche energy ^(Note 5)	E _{AS}	144	mJ
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 To 150	°C

• Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	R _{θJC}	3	°C/W
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• Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V} I_{\text{D}}=250\mu\text{A}$	60	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=60\text{V} V_{\text{GS}}=0\text{V}$	--	--	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V} V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
On Characteristics <small>(Note 3)</small>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}} I_{\text{D}}=250\mu\text{A}$	1.4	1.8	2.5	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V} I_{\text{D}}=20\text{A}$	--	23	27	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V} I_{\text{D}}=20\text{A}$	--	28	32	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V} I_{\text{D}}=20\text{A}$	--	30	--	S

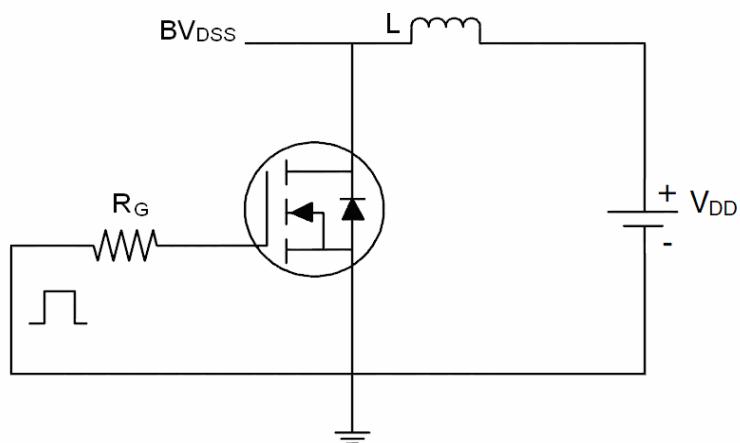
Dynamic Characteristics <small>(Note 4)</small>						
Input Capacitance	C_{iss}	$V_{\text{DS}}=30\text{V} V_{\text{GS}}=0\text{V}$ $F=1.0\text{MHz}$	--	1900	--	PF
Output Capacitance	C_{oss}		--	130	--	PF
Reverse Transfer Capacitance	C_{rss}		--	95	--	PF
Switching Characteristics <small>(Note 4)</small>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=30\text{V} I_{\text{D}}=20\text{A}$ $V_{\text{GS}}=10\text{V} R_{\text{G}}=3\Omega$	--	5	--	nS
Turn-on Rise Time	t_r		--	2.6	--	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		--	16	--	nS
Turn-Off Fall Time	t_f		--	2.3	--	nS
Total Gate Charge	Q_g	$V_{\text{DS}}=30\text{V} I_{\text{D}}=20\text{A}$ $V_{\text{GS}}=10\text{V}$	--	30	--	nC
Gate-Source Charge	Q_{gs}		--	4.5	--	nC
Gate-Drain Charge	Q_{gd}		--	7.5	--	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <small>(Note 3)</small>	V_{SD}	$V_{\text{GS}}=0\text{V} I_{\text{S}}=30\text{A}$	--	--	1.2	V
Diode Forward Current <small>(Note 2)</small>	I_{S}		--	--	30	A

Notes:

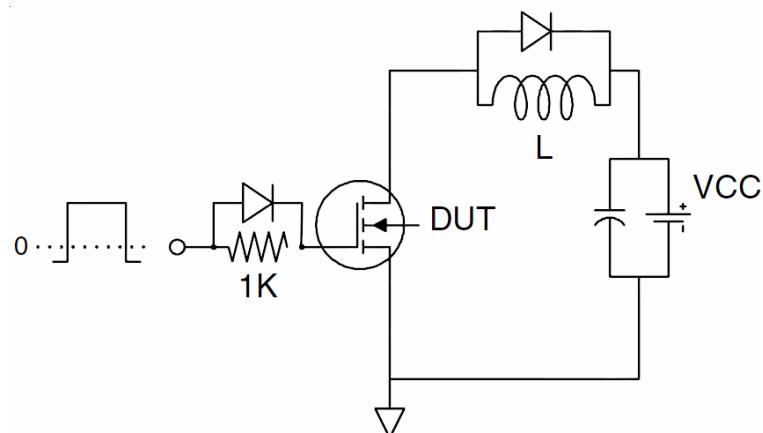
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_j=25^\circ\text{C}, V_{\text{DD}}=10\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_{\text{G}}=25\Omega$

• Test circuit

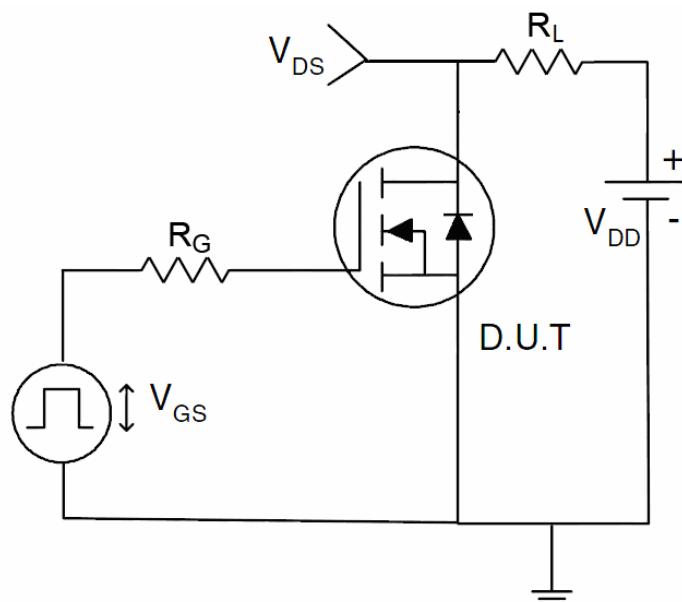
1) E_{AS} test Circuit



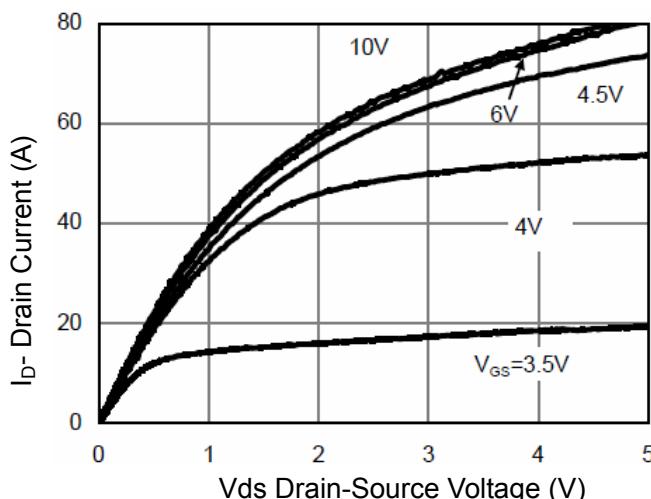
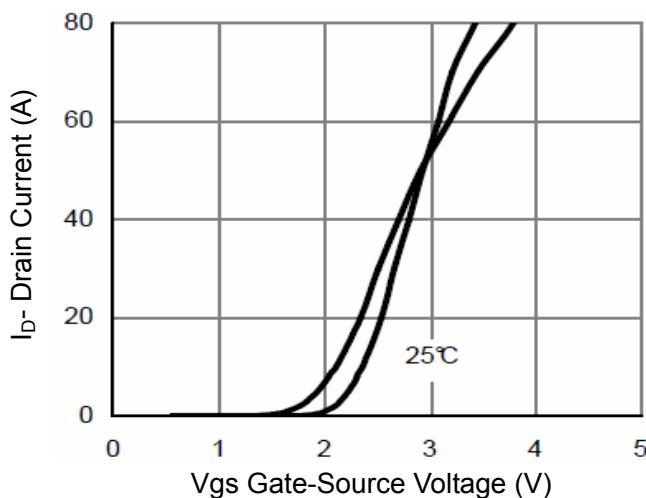
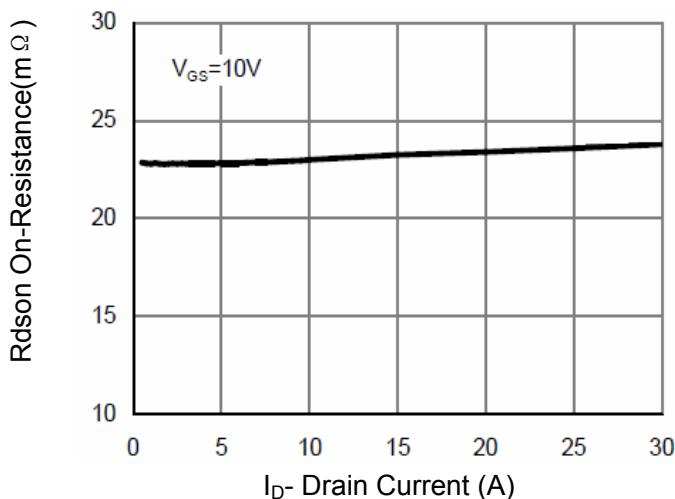
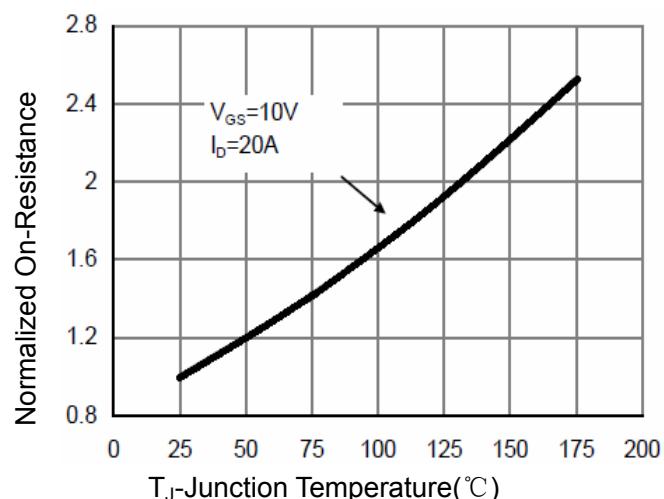
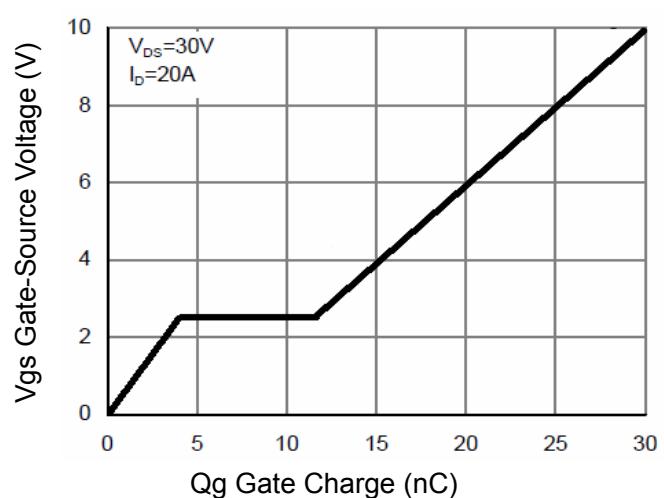
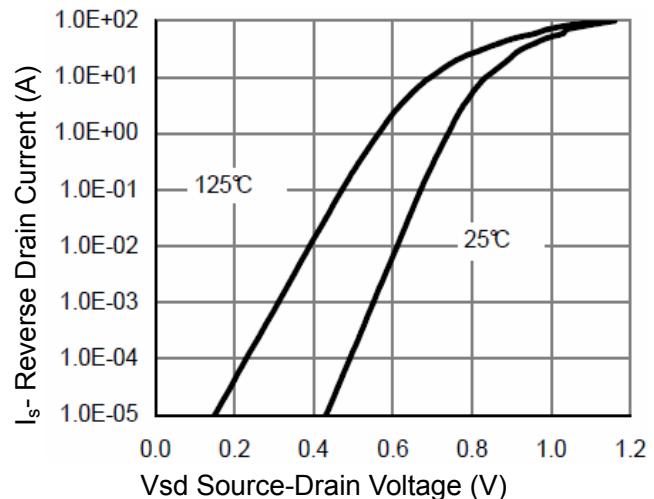
2) Gate charge test Circuit

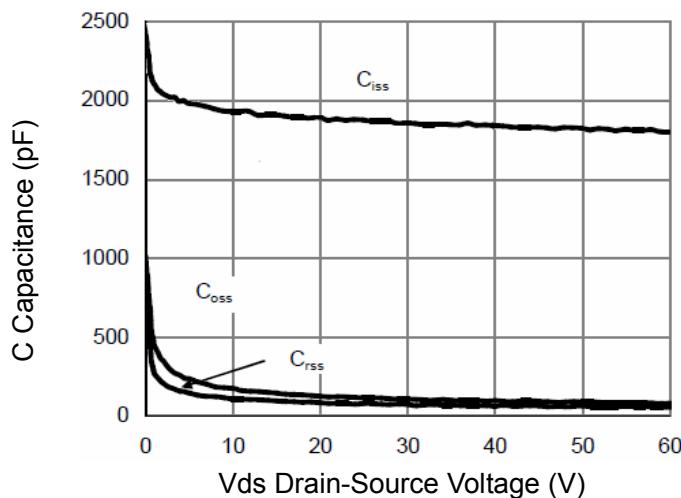
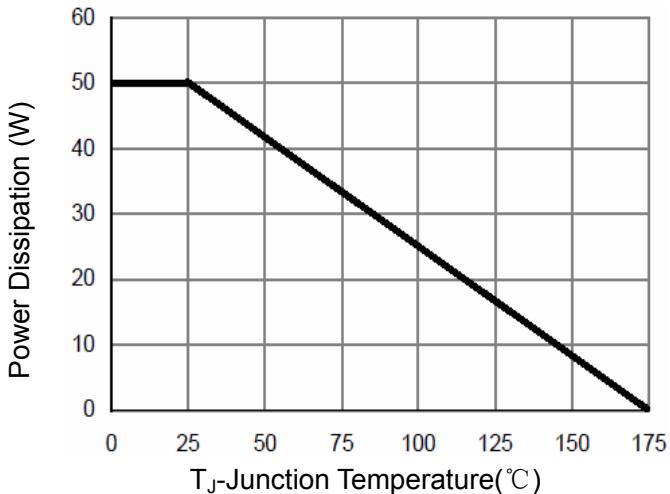
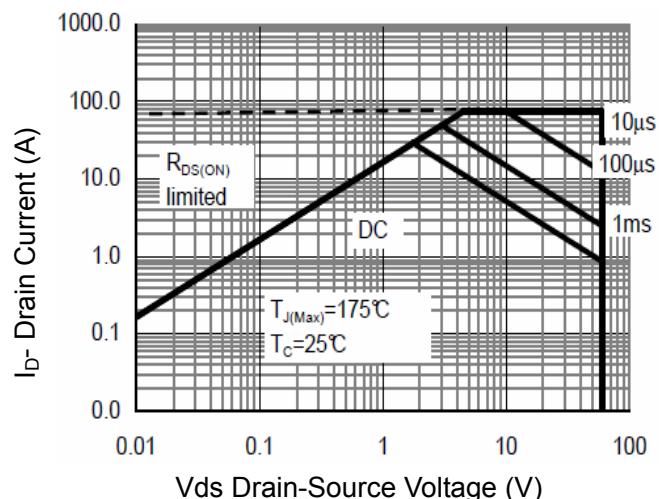
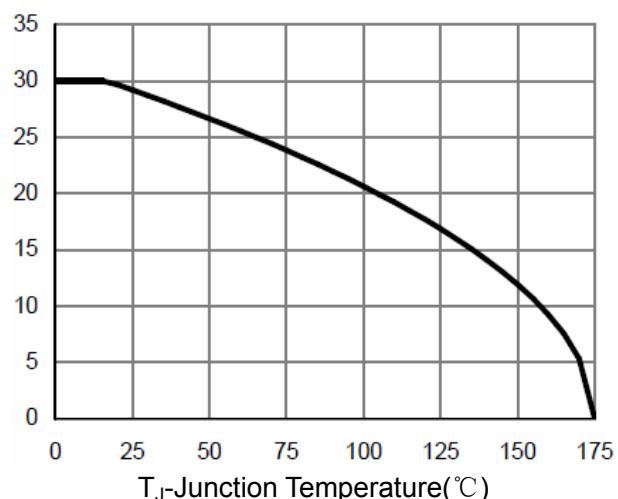
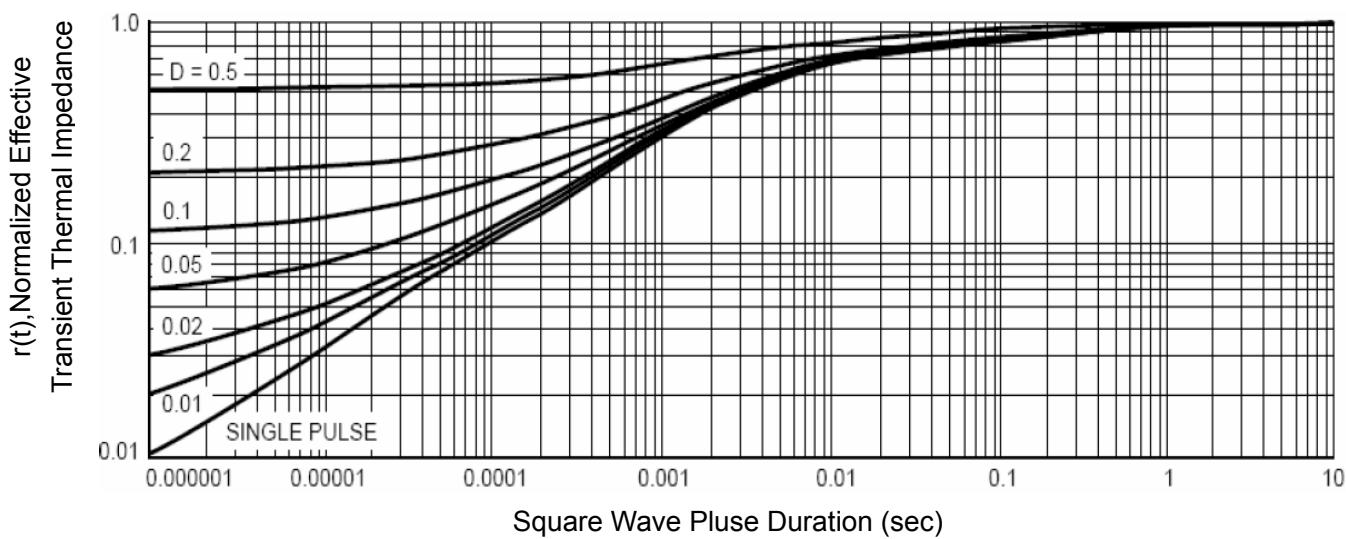


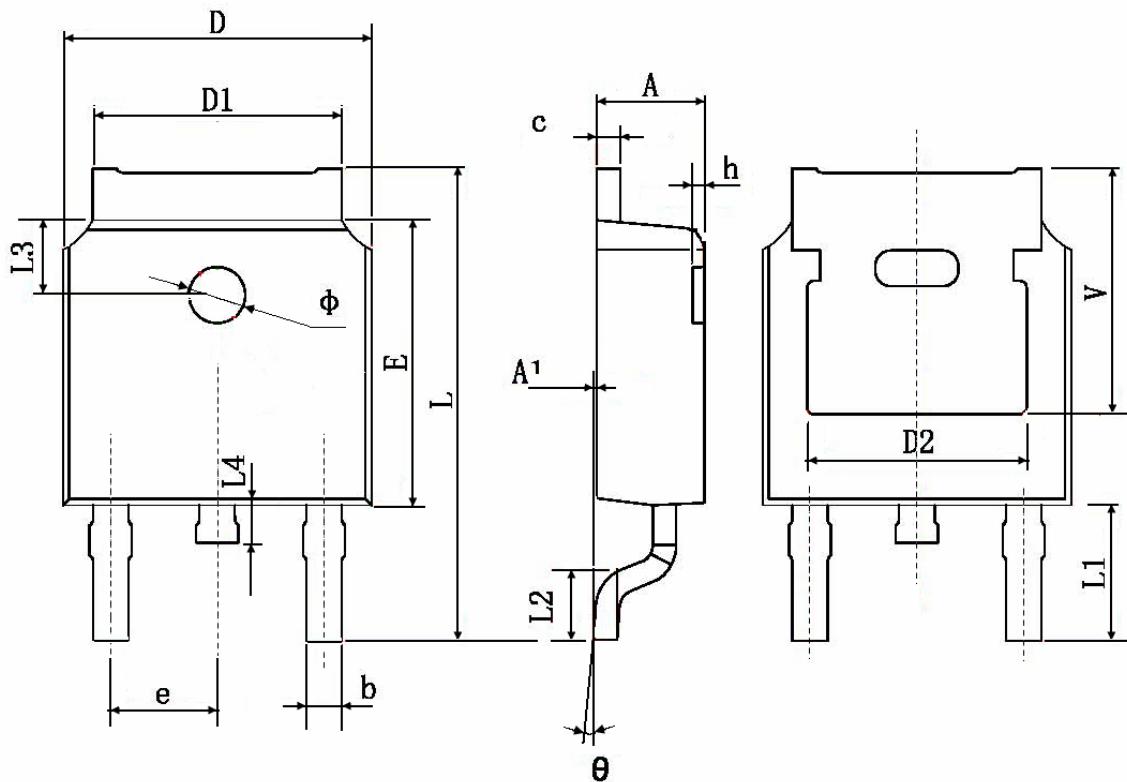
3) Switch Time Test Circuit



• Typical Characteristics


Figure 1 Output Characteristics

Figure 2 Transfer Characteristics

Figure 3 Rdson- Drain Current

Figure 4 Rdson-Junction Temperature

Figure 5 Gate Charge

Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 $V_{GS(\text{th})}$ vs Junction Temperature

Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.83 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	